Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.129”**

**PAD FUNCTIONS:**

1. **V IN (2 bond pads)**
2. **V OUT (2 bond pads)**
3. **V OUT SENSE**
4. **ADJUST**

**ANODE**

**.015”**

**.015”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004 x .004”**

**Backside Potential: CATHODE**

**APPROVED BY: DK DIE SIZE .015” X .015” DATE: 1/30/23**

**MFG: FAIRCHILD THICKNESS .007” P/N: 1N3600**

**DG 10.1.2**

#### Rev B, 7/1